

FORM PTO-1083

In re Application of: Shinji TAKEDA et al.

Serial No. 09/785,435

Filed: February 20, 2001

For: SEMICONDUCTOR DEVICE AND PROCESS FOR FABRICATION THEREOF

ASSISTANT COMMISSIONER FOR PATENTS

Box: Fee Amendment

Washington, D. C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- [ ] Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.  
[ ] A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is hereby claimed.  
[ XXX ] No additional fee is required.

The fee has been calculated as shown below:

(COL. 1)			(COL. 2)			(COL. 3)			SMALL ENTITY		OTHER THAN A SMALL ENTITY	
CLAIMS REMAINING AFTER AMENDMENT			HIGHEST NO. PREVIOUSLY PAID FOR			PRESENT EXTRA			ADDIT. OR RATE FEE		ADDIT. RATE FEE	
TOTAL	*	17	MINUS	**	53	=	0		X 9 = \$		X 18 = \$	0
INDEP.	*	5	MINUS	***	17	=	0		X 42 = \$		X 84 = \$	0
[ ] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM									X140 = \$		X280 = \$	
TOTAL												
ADDIT. FEE \$ _____ OR TOTAL \$ _____ -0-												

- \* If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.  
\*\* If the "Highest No. Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.  
\*\*\* If the "Highest No. Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space.  
The "Highest No. Previously Paid For" (Total or Independent) is the highest number found from the equivalent box in Col. 1 of a prior Amendment or the number of claims originally filed.

- [ ] Please charge my Deposit Account No. 501281 in the amount of \$ \_\_\_\_\_. A duplicate copy of this sheet is attached.  
[ ] A check (No. \_\_\_\_\_) in the amount of \$ \_\_\_\_\_ is attached.  
[ XXX ] The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 501281. A duplicate copy of this sheet is attached.

- [XX] Any filing fees under 37 CFR 1.16 for the presentation of extra claims.  
[XX] Any patent application processing fees under 37 CFR 1.17.

Joerg-Uwe Szipl  
Reg. No. 31,799

PLEASE DIRECT ALL CORRESPONDENCE TO:

GRIFFIN & SZIPL, PC  
Suite PH-1, 2300 9th Street, South  
Arlington, VA 22204

Telephone: (703) 979-5700  
Facsimile: (703) 979-7429  
Customer No.: 24203



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of )  
Shinji TAKEDA et al. ) Atty. Docket No.: TM&K0007  
Serial No. 09/785,436 ) Group Art Unit: 2813  
Filed: February 20, 2001 ) Examiner: Scott Geyer  
For: SEMICONDUCTOR DEVICE AND )  
PROCESS FOR FABRICATION ) Date: March 25, 2002  
THEREOF )

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AMENDMENT (C)

**BOX: Fee Amendment**  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the official Office Action dated September 25, 2001, please amend the above-captioned application as follows:

IN THE CLAIMS

- ✓ Please cancel claims 25-28, 30, 32-35 and 39-48 without prejudice.
- ✓ Kindly add new claims 49-60 as follows:

49. (NEW) A process for fabricating a semiconductor device according to claim 38,  
C<sup>1</sup> wherein said process is performed with said filmy die-bonding material comprising polyimide  
and epoxy resin comprising one or more resins selected from the group consisting of silicone  
resin, acrylic resin, polyimide resin and epoxy resin; and  
said filmy die-bonding material has a water absorption of 1.5% by volume or less.